

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHENG-KANG WANG</td> <td>10/28/2009</td> </tr> <tr> <td>HOU-WEI LIN</td> <td>10/28/2009</td> </tr> <tr> <td>CHIA-CHUN HUNG</td> <td>10/28/2009</td> </tr> </tbody> </table>		Name	Execution Date	CHENG-KANG WANG	10/28/2009	HOU-WEI LIN	10/28/2009	CHIA-CHUN HUNG	10/28/2009		
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CORRESPONDENCE DATA											
<p>Fax Number: (312)427-6663 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 3124271300 Email: nicholas.kubacki@ladas.net Correspondent Name: RICHARD J. STREIT Address Line 1: LADAS & PARRY, 224 SOUTH MICHIGAN AVE. Address Line 4: CHICAGO, ILLINOIS 60604</p>											
ATTORNEY DOCKET NUMBER:	CU-7902 BWH/NK										
NAME OF SUBMITTER:	Brian W. Hameder										
<p>Total Attachments: 2 source=cu7902assign#page1.tif source=cu7902assign#page2.tif</p>											

CH \$40.00 12613059

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PATENT
 REEL: 023477 FRAME: 0059

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)
PARITY-CHECK-CODE DECODER AND RECEIVING SYSTEM

The PATENT RIGHTS referred to in this agreement are:

- (check one) ☒ a patent application for this invention, executed by the
ASSIGNOR(S) concurrently with this assignment.
- ☐ U.S. patent application Serial No. _____, filed _____
- ☐ a U.S. patent application based on PCT International Application
No. _____, filed on (date) _____ (U.S. patent
application Serial No. _____, if known)
- ☐ U.S. Patent No. _____, issued _____

The PATENT RIGHTS also include all divisions, reissues, continuations and
extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- (check one) ☒ U.S. patent rights only.
- ☐ Worldwide patent rights. In this case, the assignee shall have the
right to claim the benefit of the filing date of any U.S. or foreign
patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose
signature(s) appear(s) on page 2 of this Assignment and any Supplemental Sheets(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) Realtek Semiconductor Corp.

(Address) No. 2, Innovation Rd. II, Hsinchu Science Park, Hsinchu 30076, Taiwan

The ASSIGNEE is:

- (check one) ☐ An Individual.
- ☐ A Partnership.
- ☒ A Corporation of Taiwan (specify state or country)
- ☐ (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other
good and valuable consideration, receipt of which is acknowledged, hereby assign(s)
the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;
the entire right, title and interest in and to the PATENT RIGHTS;
the right to sue and recover for any past infringement; and,
the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the commissioner of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) any attorney and agent who has a power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Cheng-Kang WANG</u>	<u>Cheng Kang, Wang</u>	<u>Oct. 28, 2009</u>
Name of sole or first inventor	Signature	Date

<u>Hou-Wei LIN</u>	<u>Hou Wei Lin</u>	<u>Oct. 28, 2009</u>
Name of second inventor, if any	Signature	Date

<u>Chia-Chun HUNG</u>	<u>Chia Chun, Hung</u>	<u>Oct. 28, 2009</u>
Name of third inventor, if any	Signature	Date

_____ Name of fourth inventor, if any	_____ Signature	_____ Date
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_____ Name of fifth inventor, if any	_____ Signature	_____ Date
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